



Material Content Data Sheet



Halogen-Free

Sales Product Name	TLE7258SJ	Issued	24. February 2022
MA#	MA005708301		
Package	PG-DSO-8-44	Weight*	82.63 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.828	1.00	1.00	10019	10019
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.036	0.04		434	
	non noble metal	iron	7439-89-6	0.717	0.87		8679	
	non noble metal	copper	7440-50-8	29.121	35.24	36.16	352415	361636
wire	non noble metal	copper	7440-50-8	0.061	0.07	0.07	733	733
encapsulation	organic material	carbon black	1333-86-4	0.100	0.12		1212	
	plastics	epoxy resin	-	4.606	5.57		55740	
	inorganic material	silicondioxide	60676-86-0	45.359	54.91	60.60	548918	605870
leadfinish	non noble metal	tin	7440-31-5	0.814	0.98	0.98	9849	9849
plating	noble metal	silver	7440-22-4	0.650	0.79	0.79	7869	7869
glue	plastics	acrylic resin	-	0.073	0.09		885	
	noble metal	silver	7440-22-4	0.259	0.31	0.40	3139	4024
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com